



Material Content Data Sheet



Sales Product Name		BSZ028N04LS		Issued		1. August 2018		
MA#		MA001075720						
Package		PG-TSDSON-8-26		Weight*		36.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.552	1.51	1.51	15059	15059
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		268	
	non noble metal	iron	7439-89-6	0.197	0.54		5365	
wire	non noble metal	copper	7440-50-8	7.988	21.78	22.36	217848	223548
	noble metal	gold	7440-57-5	0.028	0.08	0.08	770	770
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1009	
	plastics	epoxy resin	-	1.906	5.20		51979	
	inorganic material	silicondioxide	60676-86-0	16.562	45.15	50.45	451664	504652
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10779	10779
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	554	554
solder	non noble metal	tin	7440-31-5	0.017	0.05		455	
	noble metal	silver	7440-22-4	0.021	0.06		569	
	non noble metal	lead	7439-92-1	0.797	2.17	2.28	21745	22769
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2563	
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.41	10.68	104063	106786
	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2762	
*deviation	non noble metal	copper	7440-50-8	4.112	11.21	11.50	112148	115083
						Sum in total:	100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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